

L-937SURKCGKW

T-1(3mm) Bi-Color Indicator Lamp



DESCRIPTIONS

- The Hyper Red source color devices are made with AlGaInP on GaAs substrate Light Emitting Diode
- The Green source color devices are made with AIGaInP on GaAs substrate Light Emitting Diode
- · Electrostatic discharge and power surge could damage the LEDs
- It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs
- · All devices, equipments and machineries must be electrically grounded

FEATURES

- Uniform light output
- · Low power consumption
- Long life solid state reliability
- Halogen-free
- RoHS compliant

APPLICATIONS

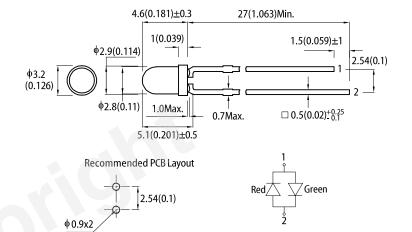
- Status indicator
- Illuminator
- Signage applications
- Decorative and entertainment lighting
- · Commercial and residential architectural lighting

ATTENTION

Observe precautions for handling electrostatic discharge sensitive devices



PACKAGE DIMENSIONS



- Notes All dimensions are in millimeters (inches)
- An uninensions are in minimiters (incres).
 Tolerance is ±0.25(0.01") unless otherwise noted.
 Lead spacing is measured where the leads emerge from the package.
 The specifications, characteristics and technical data described in the datasheet are subject to change ithout prior notice

SELECTION GUIDE

Part Number	Emitting Color (Material)	Lens Type	lv (mcd) @ 20mA ^[2]		Viewing Angle ^[1]	
			Min.	Тур.	201/2	
L-937SURKCGKW	Hyper Red (AlGaInP)	White Diffused	200	500		
			*55	*110	60°	
	Green (AlGaInP)		40	80	00	
			*40	*80		

Notes

1. 01/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
 2. Luminous intensity / luminous flux: +/-15%.
 * Luminous intensity value is traceable to CIE127-2007 standards.

ELECTRICAL / OPTICAL CHARACTERISTICS at T_A=25°C

Parameter	Symbol	Emitting Color	Value		l Init
Falameter			Тур.	Max.	Unit
Wavelength at Peak Emission $I_F = 20 \text{mA}$	λ_{peak}	Hyper Red Green	645 574	-	nm
Dominant Wavelength I _F = 20mA	λ_{dom} ^[1]	Hyper Red Green	630 570	-	nm
Spectral Bandwidth at 50% Φ REL MAX I _F = 20mA	Δλ	Hyper Red Green	28 20	-	nm
Forward Voltage I _F = 20mA	V _F ^[2]	Hyper Red Green	1.95 2.1	2.5 2.5	V
Temperature Coefficient of λ_{peak} I_F = 20mA, -10°C $\leq T \leq 85°C$	TC_{\lambdapeak}	Hyper Red Green	0.14 0.12	-	nm/°C
Temperature Coefficient of λ_{dom} I_F = 20mA, -10°C $\leq T \leq 85°C$	$TC_{\lambda dom}$	Hyper Red Green	0.05 0.08	-	nm/°C
Temperature Coefficient of V_F I_F = 20mA, -10°C \leq T \leq 85°C	TCv	Hyper Red Green	-1.9 -2.0	-	mV/°C

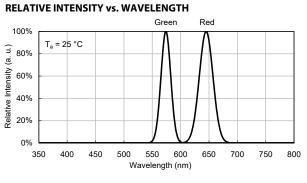
Notes: 1. The dominant wavelength (λd) above is the setup value of the sorting machine. (Tolerance λd : ±1nm.) 2. Forward voltage: ±0.1V. 3. Wavelength value is traceable to CIE127-2007 standards. 4. Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

ABSOLUTE MAXIMUM RATINGS at T_A=25°C

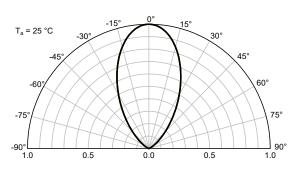
Parameter	Symbol	Va	l la it	
Parameter		Hyper Red	Green	Unit
Power Dissipation	PD	75	75	mW
Junction Temperature	Tj	115	115	°C
Operating Temperature	T _{op}	-40 to +85		°C
Storage Temperature	T _{stg}	-40 to +85		°C
DC Forward Current	I _F	30	30	mA
Peak Forward Current	I _{FP} ^[1]	185	150	mA
Electrostatic Discharge Threshold (HBM)	-	3000	3000	V
Thermal Resistance (Junction / Ambient)	R _{th JA} ^[2]	680	770	°C/W
Thermal Resistance (Junction / Solder point)	R _{th JS} ^[2]	460	510	°C/W
Lead Solder Temperature ^[3]		260°C For 3 Seconds		
Lead Solder Temperature ^[4]		260°C For 5 Seconds		

Notes: 1. 1/10 Duty Cycle, 0.1ms Pulse Width. 2. R_{th Js}, Results from mounting on PC board FR4 (pad size ≥ 16 mm² per pad). 3. 2mm below package base. 4. 5mm below package base. 5. Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity – Ref JEDEC/JESD625-A and JEDEC/J-STD-033.

TECHNICAL DATA



SPATIAL DISTRIBUTION



at

Luminous intensity normalised

Forward Voltage 50 at T_a = 25 °C Luminous intensity normalised 40 Forward current (mA) 30 20 10 0 1.5 1.7 1.9 2.1 2.3 2.5

Forward voltage (V)

HYPER RED

Luminous Intensity vs.

Forward current (mA)

30 40 50

Forward Current

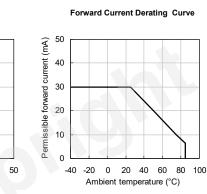
T_a = 25 °C

1.0

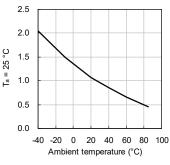
0.5

0.0

0 10 20 30 40



Luminous Intensity vs. Ambient Temperature

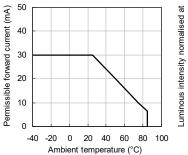




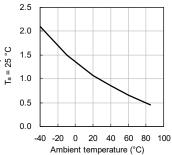
Forward Current vs. Luminous Intensity vs. Forward Voltage **Forward Current** 50 2.5 Luminous intensity normalised at T_a = 25 °C T_a = 25 °C Forward current (mA) 40 2.0 30 20 mA 1.5 20 1.0 10 0.5 0 0.0 17 19 21 23 25 0 20 15 10 Forward voltage (V) Forward current (mA)



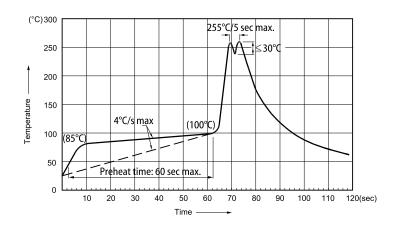
Forward Current Derating Curve



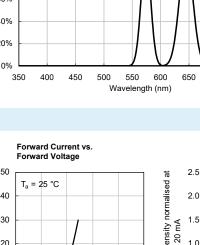
Luminous Intensity vs. Ambient Temperature



RECOMMENDED WAVE SOLDERING PROFILE

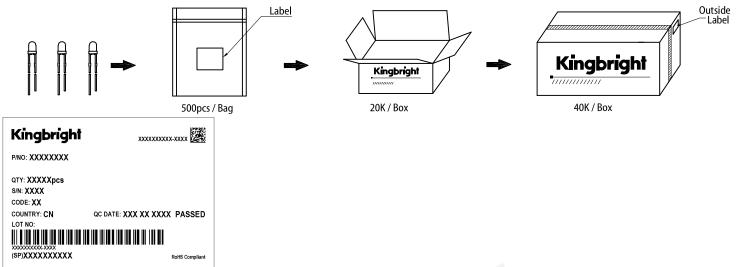


- Notes: 1. Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple Recommend pre-heat temperature of 105°C or less (as measured with a thermocuple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260°C
 Peak wave soldering temperature between 245°C ~ 255°C for 3 sec (5 sec max).
 Do not apply stress to the epoxy resin while the temperature is above 85°C.
 Fixtures should not incur stress on the component when mounting and during soldering process.
 SAC 305 solder alloy is recommended.
 No more than one wave soldering pass.



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PACKING & LABEL SPECIFICATIONS



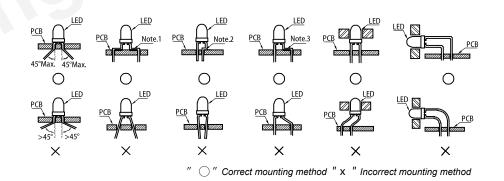
PRECAUTIONS

Storage Conditions

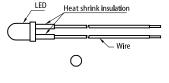
- 1. Avoid continued exposure to the condensing moisture environment and keep the product away from rapid transitions in ambient temperature.
- 2. The LEDs should be stored at temperature <30°C and relative humidity <70%. If the packaging is opened but not used within three months, the unused LEDs should be stored in a sealed container with nitrogen atmosphere and moisture absorbent material.

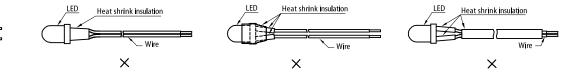
LED Mounting Method

 The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures. Note 1-3: Do not route PCB trace in the contact area between the leadframe and the PCB to prevent short-circuits.



2. When soldering wires to the LED, each wire joint should be separately insulated with heat-shrink tube to prevent short-circuit contact. Do not bundle both wires in one heat shrink tube to avoid pinching the LED leads. Pinching stress on the LED leads may damage the internal structures and cause failure.



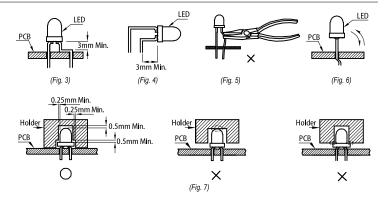


- PCB Stand-off (Fig. 1) (Fig. 2)
- 3. Use stand-offs (*Fig.1*) or spacers (*Fig.2*) to securely position the LED above the PCB.
 4. Maintain a minimum of 3mm clearance between the base of the LED lens and the first lead bend (*Fig. 3*, *Fig. 4*).
- 5. During lead forming, use tools or jigs to hold the leads securely so that the bending force will not be transmitted to the LED lens and its internal structures. Do not perform lead forming once the component has been mounted onto the PCB. (*Fig. 5*)

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Lead Forming Procedures

- 1. Do not bend the leads more than twice. (Fig. 6)
- 2. During soldering, component covers and holders should leave clearance to avoid placing damaging stress on the LED during soldering. (Fig. 7)
- 3. The tip of the soldering iron should never touch the lens epoxy.
- 4. Through-hole LEDs are incompatible with reflow soldering.
- 5. If the LED will undergo multiple soldering passes or face other processes where the part may be subjected to intense heat, please check with Kingbright for compatibility.



PRECAUTIONARY NOTES

- 1. 2.
- The information included in this document reflects representative usage scenarios and is intended for technical reference only. The part number, type, and specifications mentioned in this document are subject to future change and improvement without notice. Before production usage customer should refer to the latest datasheet for the updated specifications.
- When using the products referenced in this document, please make sure the product is being operated within the environmental and electrical limits specified in the datasheet. If 3. customer usage exceeds the specified limits, Kingbright will not be responsible for any subsequent issues.
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- 5. 6.
- All design applications should refer to Kingbright application notes available at http